

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

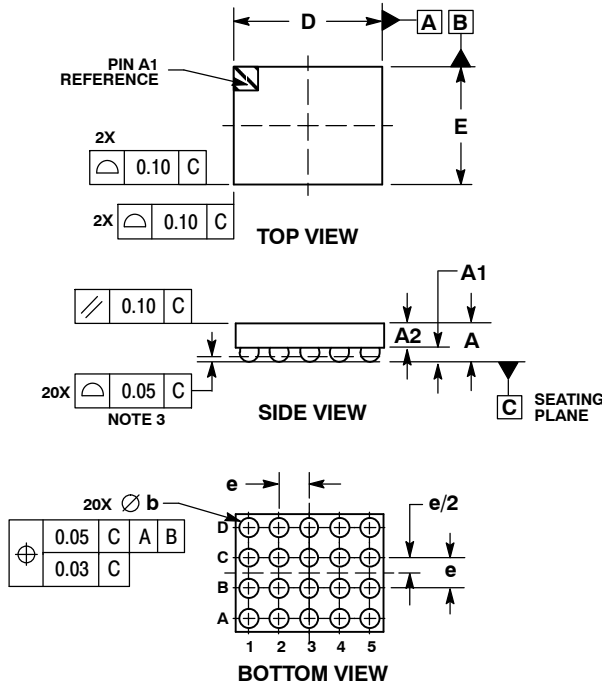


A1

SCALE 4:1

20 PIN FLIP-CHIP, 2.5x2.0, 0.5P
CASE 499BH-01
ISSUE A

DATE 22 OCT 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
4. DIE COAT, 0.04 THICK, PERMISSABLE ON THIS SURFACE. DIE COAT THICKNESS IS INCLUDED IN DIMENSIONS A AND A2.

DIM	MILLIMETERS	
	MIN	MAX
A	0.54	0.66
A1	---	0.27
A2	0.33	0.39
b	0.29	0.34
D	2.50 BSC	
E	2.00 BSC	
e	0.50 BSC	

GENERIC MARKING DIAGRAM*



XXXXXXXX = Specific Device Code

A = Assembly Location

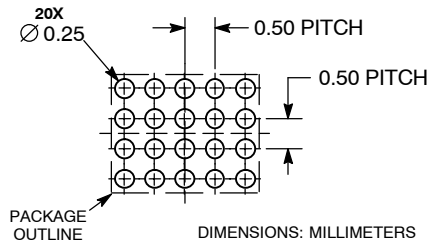
Y = Year

WW = Work Week

▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDER FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	20 PIN FLIP-CHIP, 2.5 X 2.0, 0.5P	PAGE 1 OF 2

